

09/365,356

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|---|------------------|
| 1 | 2791 | ((257/701) or (438/125) or (438/118)).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/23 14:57 |
| 2 | 1638 | ((((257/701) or (438/125) or (438/118)).CCLS.) and @ad<19990730 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/23 14:58 |
| 3 | 321 | (((((257/701) or (438/125) or (438/118)).CCLS.) and @ad<19990730). and (adhesiv\$3 adher\$3) and (interposer carrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/23 15:00 |
| 4 | 22 | (((((257/701) or (438/125) or (438/118)).CCLS.) and @ad<19990730) and (strip near4 (adhesiv\$3 adher\$3)) and (interposer carrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/23 15:09 |
| 5 | 1266 | (interposer carrier) and @ad<19990730 and (strip near3 (adher\$3 adhesiv\$3)) and (semiconductor chip die dice ic (integrated adj circuit)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/23 15:11 |
| 6 | 30 | ((polyimide organic) near4 (interposer carrier)) and @ad<19990730 and (strip near3 (adher\$3 adhesiv\$3)) and (semiconductor chip die dice ic (integrated adj circuit)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/23 15:11 |
| 7 | 100 | ((polyimide organic) near4 (interposer carrier substrate)) and @ad<19990730 and (strip near3 (adher\$3 adhesiv\$3)) and (semiconductor chip die dice ic (integrated adj circuit)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/23 15:12 |